

Appln. No. 10/532,949
Response dated December 23, 2008 to
Reply to Final Office Action of October 3, 2008

REMARKS

Reconsideration of the present application, as amended, is respectfully requested.

The October 3, 2008 Final Office Action and the Examiner's comments have been carefully considered. In response, claims are amended, and remarks are set forth below in a sincere effort to place the present application in form for allowance. The amendments are supported by the application as originally filed. Therefore, no new matter is added.

PRIOR ART REJECTIONS

In the Office Action, claims 1-3, 5-7 and 16 are rejected under the second paragraph of 35 USC 102(b) as being anticipated by USP 6,603,647 (Chen et al.), or, in the alternative, under 35 USC 103(a) as obvious over Chen et al. in view of Applicants' Admitted Prior Art (AAPA). Claims 4 and 17-19 are rejected under 35 USC 103(a) as being unpatentable over Chen et al. or Chen et al/AAPA further in view of USP 5,352,314 (Coplan).

In the Office Action, the Examiner appears to contend that the structural element 36 of Chen et al. corresponds to the weak-adherence adhesive pattern of the present invention. However, element 36 of Chen et al. is nothing more than an inter-layer insulating film provided between two circuit elements (i.e., substrates on which conductive parts are

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provided). More specifically, this inter-layer insulating film is originally provided on the entire surface of the substrate 22 of the structural element 20 (see Fig. 1a) and as shown in Fig. 1b, at least a part of the insulating layer 36 is removed, so as to expose a part of the bump 30, which is provided between the two circuit elements when they are combined. In Fig. 1b, an abrasive material 40 (sand paper or the like) is used for "removing at least a part of the insulating layer 36."

Additionally, in the Office Action, the Examiner states that the substrate (22) of Chen et al. is for affixing/holding/attaching to the printed circuit board (23). However, in Chen et al., both elements are called the "substrate 22, 23," that is, both are two equal circuit substrates (on which conductive parts are provided).

In contrast, the "plate" of the present claimed invention is a base on which a printed circuit board or a conductive material laminated plate for manufacturing the printed circuit board is detachably held, and thus not a substrate having an electric circuit element.

Therefore, the structure disclosed in Chen et al. does not disclose, teach or suggest a holding and conveyance jig for detachably holding and conveying a printed circuit board or a conductive material laminated plate for manufacturing said printed circuit board, or a method, but relates to a different

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technical field for adhesion of two equal substrates having electric circuit elements. Accordingly, Chen et al. does also not relate to a specific object of the present invention (for solving problems of a conventional holding and conveyance jig).

That is, in the structure of Chen et al., (i) the circuit elements of the substrates 22 and 23 are conductive to each other via the pads 24 and 25 which are respectively provided on the substrates 22 and 23 (see lines 48-52 at column 4 of Chen et al.), (ii) one of the substrates 22 and 23 is not used for conveying the other substrate, and (iii) the other substrate is not detached after both substrates are adhered to each other.

In contrast, the present claimed invention is directed to a holding and conveyance jig for detachably holding and conveying a printed circuit board or a conductive material laminated plate for manufacturing said printed circuit board. As such, a printed circuit board or a conductive material laminated plate is placed and held on the plate of the holding and conveyance jig, the plate of the holding and conveyance jig has no electric circuit element, and functions as a base. In addition, the held printed circuit board or conductive material laminated plate can be detached after a specific process is completed.

Accordingly, the present claimed invention is patentable over Chen et al.

Applicants' admitted prior art (AAPA) does not close the

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gap between the present claimed invention as defined by the independent claims and Chen et al. Therefore, the independent claims are patentable over Chen et al. and AAPA when taken either singly under 35 USC 102 or in combination under 35 USC 103.

None of the other references of record close the gap between the present claimed invention as defined by the independent claims and Chen et al., taken either alone or in combination under the AAPA. Therefore, the independent claims are patentable over all of the references of record under 35 USC 102 as well as 35 USC 103.

Dependent claims 3-5 and 16-19 are either directly or indirectly dependent on claim 2 and are patentable over the cited references for reasons set forth above in connection with the independent claims and because the references do not disclose, teach or suggest each of the limitations set forth in claims 3-5 and 16-19. Therefore, in view of all of the foregoing, claims 1-7 and 16-19 are in form for immediate allowance, which action is earnestly solicited.

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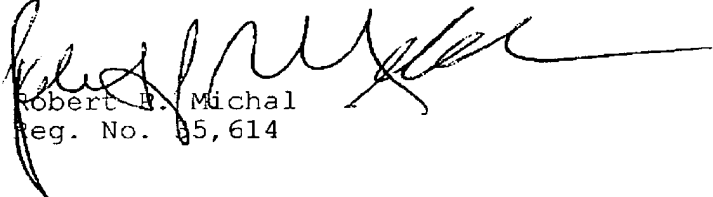
Entry of this Amendment, allowance of the claims and the passing of this application to issue are respectfully solicited.

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If the Examiner disagrees with any of the foregoing, the Examiner is respectfully requested to point out where there is support for a contrary view.

If the Examiner has any comments, questions, objections or recommendations, the Examiner is invited to telephone the undersigned at the telephone number given below for prompt action.

Respectfully submitted,



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